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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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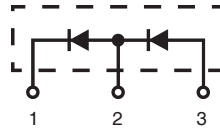
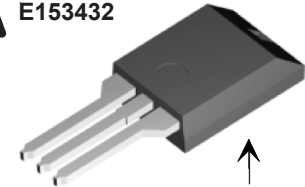
HiPerDynFRED™ Epitaxial Diode**ISOPLUS220™****Electrically Isolated Back Surface**

$$I_{FAV} = 6 \text{ A}$$

$$V_{RRM} = 600 \text{ V}$$

$$t_{rr} = 20 \text{ ns}$$

$V_{RRM}^{①}$ V	V_{RRM} V	Type
600	300	DSEE 6-06CC

ISOPLUS 220
E153432

Isolated back surface*

Symbol	Conditions	Maximum Ratings	
I_{FRMS}		20	A
I_{FAVM}	$T_C = 150^\circ\text{C}$; rectangular, $d = 0.5$	6	A
E_{AS}	$T_{VJ} = 25^\circ\text{C}$; non-repetitive $I_{AS} = 0.8 \text{ A}$; $L = 180 \mu\text{H}$	0.1	mJ
I_{AR}	$V_A = 1.5 \cdot V_R$ typ.; $f = 10 \text{ kHz}$; repetitive	0.1	A
T_{VJ}		-40...+175	$^\circ\text{C}$
T_{VJM}		175	$^\circ\text{C}$
T_{sig}		-40...+150	$^\circ\text{C}$
P_{tot}	$T_C = 25^\circ\text{C}$	50	W
V_{ISOL}	50/60 Hz RMS; $I_{ISOL} \leq 1 \text{ mA}$	2500	V~
F_C	Mounting force	11...65 / 2.4...11	N / lb
Weight	typical	2	g

Features

- λ Silicon chip on Direct-Copper-Bond substrate
- High power dissipation
- Isolated mounting surface
- 2500V electrical isolation
- λ Low cathode to tab capacitance (<15pF)
- λ Planar passivated chips
- λ Very short recovery time
- λ Extremely low switching losses
- λ Low I_{RM} -values
- λ Soft recovery behaviour
- λ Epoxy meets UL 94V-0

Applications

- λ Antiparallel diode for high frequency switching devices
- λ Antisaturation diode
- λ Snubber diode
- λ Free wheeling diode in converters and motor control circuits
- λ Rectifiers in switch mode power supplies (SMPS)
- λ Inductive heating
- λ Uninterruptible power supplies (UPS)
- λ Ultrasonic cleaners and welders

Advantages

- λ Avalanche voltage rated for reliable operation
- λ Soft reverse recovery for low EMI/RFI
- λ Low I_{RM} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Symbol	Conditions	Characteristic Values	
		typ.	max.
$I_R^{①}$	$T_{VJ} = 25^\circ\text{C}$ $V_R = V_{RRM}$ $T_{VJ} = 150^\circ\text{C}$ $V_R = V_{RRM}$		25 μA 0.2 mA
$V_F^{③}$	$I_F = 10 \text{ A}$; $T_{VJ} = 125^\circ\text{C}$ $T_{VJ} = 25^\circ\text{C}$		1.35 V 1.8 V
R_{thJC} R_{thCH}		0.6	3.0 K/W K/W
t_{rr}	$I_F = 1 \text{ A}$; $-di/dt = 50 \text{ A}/\mu\text{s}$; $V_R = 30 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$	20	ns
I_{RM}	$V_R = 100 \text{ V}$; $I_F = 10 \text{ A}$; $-di_F/dt = 100 \text{ A}/\mu\text{s}$ $T_{VJ} = 100^\circ\text{C}$	2	A

Notes: Data given for $T_{VJ} = 25^\circ\text{C}$ and per diode unless otherwise specified

① Diodes connected in series

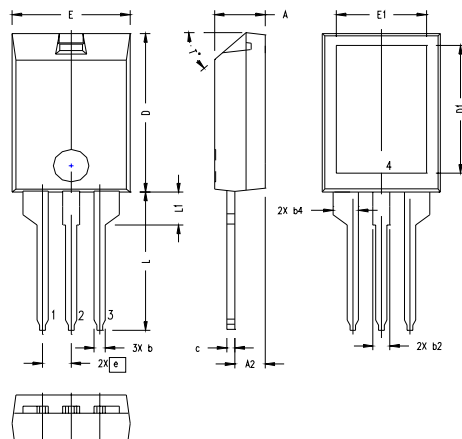
② Pulse test: pulse Width = 5 ms, Duty Cycle < 2.0 %

③ Pulse test: pulse Width = 300 μs , Duty Cycle < 2.0 %**Recommended replacement:**
DSEE8-08CC

IXYS reserves the right to change limits, test conditions and dimensions.

20080317a

ISOPLUS220 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.157	.197	4.00	5.00
A2	.098	.118	2.50	3.00
b	.035	.051	0.90	1.30
b2	.049	.065	1.25	1.65
b4	.093	.100	2.35	2.55
c	.028	.039	0.70	1.00
D	.591	.630	15.00	16.00
D1	.472	.512	12.00	13.00
E	.394	.433	10.00	11.00
E1	.295	.335	7.50	8.50
e	.100 BASIC		2.55 BASIC	
L	.512	.571	13.00	14.50
L1	.118	.138	3.00	3.50
T*			42.5*	47.5*

NOTE:

1. Bottom heatsink (Pin 4) is electrically isolated from Pin 1, 2 or 3.
2. Pin connections:
 - 1 - Cathode
 - 2 - Anode/Cathode
 - 3 - Anode